Intel - EP4CE6F17C8LN Datasheet





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Details

Product Status	Active
Number of LABs/CLBs	392
Number of Logic Elements/Cells	6272
Total RAM Bits	276480
Number of I/O	179
Number of Gates	-
Voltage - Supply	0.97V ~ 1.03V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-LBGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce6f17c8ln

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Bood Bort	Write Port								
Reau Puri	8192 × 1	4096 × 2	2048 × 4	1024 × 8	512 × 16	256 × 32	1024 × 9	512 × 18	256 × 36
512 × 16	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	—	—	—
256 × 32	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	~	—	—	—
1024 × 9	—	—	—	—	—	—	\checkmark	\checkmark	\checkmark
512 × 18		—	—	—	—	—	\checkmark	\checkmark	\checkmark
256 × 36	—	—	—	—	—	—	\checkmark	\checkmark	\checkmark

Table 3-3.	Cyclone IV Devices M9K Block Mixed-Width Configurations (Simple Dual-Port Mode)	(Part 2 of 2)
	Solono in Borroco mon Brook mixed frach Compio Baar i ort mouoj	(, a, c = 0, z)

In simple dual-port mode, M9K memory blocks support separate wren and rden signals. You can save power by keeping the rden signal low (inactive) when not reading. Read-during-write operations to the same address can either output "Don't Care" data at that location or output "Old Data". To choose the desired behavior, set the **Read-During-Write** option to either **Don't Care** or **Old Data** in the RAM MegaWizard Plug-In Manager in the Quartus II software. For more information about this behavior, refer to "Read-During-Write Operations" on page 3–15.

Figure 3–9 shows the timing waveform for read and write operations in simple dual-port mode with unregistered outputs. Registering the outputs of the RAM simply delays the q output by one clock cycle.





In this mode, the activeclock signal mirrors the clkswitch signal. As both blocks are still functional during the manual switch, neither clkbad signals go high. Because the switchover circuit is positive edge-sensitive, the falling edge of the clkswitch signal does not cause the circuit to switch back from inclk1 to inclk0. When the clkswitch signal goes high again, the process repeats. The clkswitch signal and the automatic switch only works depending on the availability of the clock that is switched to. If the clock is unavailable, the state machine waits until the clock is available.



When CLKSWITCH = 1, it overrides the automatic switch-over function. As long as clkswitch signal is high, further switch-over action is blocked.

	•
inclk0	
inclk1 _	
muxout	
clkswitch _	
activeclock _	
clkbad0 —	
clkbad1 —	

Figure 5–19. Clock Switchover Using the clkswitch Control (1)

Note to Figure 5–19:

(1) Both inclk0 and inclk1 must be running when the clkswitch signal goes high to start a manual clock switchover event.

Manual Clock Switchover

PLLs of Cyclone IV devices support manual switchover, in which the clkswitch signal controls whether inclk0 or inclk1 is the input clock to the PLL. The characteristics of a manual switchover are similar to the manual override feature in an automatic clock switchover, in which the switchover circuit is edge-sensitive. When the clkswitch signal goes high, the switchover sequence starts. The falling edge of the clkswitch signal does not cause the circuit to switch back to the previous input clock.

• For more information about PLL software support in the Quartus II software, refer to the *ALTPLL Megafunction User Guide*.

Guidelines

Use the following guidelines to design with clock switchover in PLLs:

 Clock loss detection and automatic clock switchover require the inclk0 and inclk1 frequencies be within 20% of each other. Failing to meet this requirement causes the clkbad0 and clkbad1 signals to function improperly. Figure 5–22 shows how to adjust PLL counter settings dynamically by shifting their new settings into a serial shift register chain or scan chain. Serial data shifts to the scan chain via the scandataport, and shift registers are clocked by scanclk. The maximum scanclk frequency is 100 MHz. After shifting the last bit of data, asserting the configupdate signal for at least one scanclk clock cycle synchronously updates the PLL configuration bits with the data in the scan registers.





The counter settings are updated synchronously to the clock frequency of the individual counters. Therefore, not all counters update simultaneously.

To reconfigure the PLL counters, perform the following steps:

- 1. The scanclkena signal is asserted at least one scanclk cycle prior to shifting in the first bit of scandata (D0).
- 2. Serial data (scandata) is shifted into the scan chain on the second rising edge of scanclk.
- 3. After all 144 bits have been scanned into the scan chain, the scanclkena signal is de-asserted to prevent inadvertent shifting of bits in the scan chain.
- 4. The configupdate signal is asserted for one scanclk cycle to update the PLL counters with the contents of the scan chain.
- 5. The scandone signal goes high indicating that the PLL is being reconfigured. A falling edge indicates that the PLL counters have been updated with new settings.
- 6. Reset the PLL using the areset signal if you make any changes to the M, N, post-scale output C counters, or the I_{CP}, R, C settings.
- 7. You can repeat steps 1 through 5 to reconfigure the PLL any number of times.

Table 6–2 on page 6–7 shows the possible settings for I/O standards with current strength control. These programmable current strength settings are a valuable tool in helping decrease the effects of simultaneously switching outputs (SSO) in conjunction with reducing system noise. The supported settings ensure that the device driver meets the specifications for IOH and IOL of the corresponding I/O standard.

 \square When you use programmable current strength, on-chip series termination (R_S OCT) is not available.

Slew Rate Control

The output buffer for each Cyclone IV I/O pin provides optional programmable output slew-rate control. Table 6–2 on page 6–7 shows the possible slew rate option and the Quartus II default slew rate setting. However, these fast transitions may introduce noise transients in the system. A slower slew rate reduces system noise, but adds a nominal delay to rising and falling edges. Because each I/O pin has an individual slew-rate control, you can specify the slew rate on a pin-by-pin basis. The slew-rate control affects both the rising and falling edges. Slew rate control is available for single-ended I/O standards with current strength of 8 mA or higher.

- You cannot use the programmable slew rate feature when using OCT with calibration.
- You cannot use the programmable slew rate feature when using the 3.0-V PCI, 3.0-V PCI-X, 3.3-V LVTTL, or 3.3-V LVCMOS I/O standards. Only the fast slew rate (default) setting is available.

Open-Drain Output

Cyclone IV devices provide an optional open-drain (equivalent to an open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (for example, interrupt and write enable signals) that are asserted by multiple devices in your system.

Bus Hold

Each Cyclone IV device user I/O pin provides an optional bus-hold feature. The bus-hold circuitry holds the signal on an I/O pin at its last-driven state. Because the bus-hold feature holds the last-driven state of the pin until the next input signal is present, an external pull-up or pull-down resistor is not necessary to hold a signal level when the bus is tri-stated.

The bus-hold circuitry also pulls undriven pins away from the input threshold voltage in which noise can cause unintended high-frequency switching. You can select this feature individually for each I/O pin. The bus-hold output drives no higher than $V_{\rm CCIO}$ to prevent overdriving signals.

IF you enable the bus-hold feature, the device cannot use the programmable pull-up option. Disable the bus-hold feature when the I/O pin is configured for differential signals. Bus-hold circuitry is not available on dedicated clock pins.

Bus-hold circuitry is only active after configuration. When going into user mode, the bus-hold circuit captures the value on the pin present at the end of configuration.

Table 6–2 lists the I/O standards that support impedance matching and series termination.

I/O Standard	IOH/IOL Current Strength Setting (mA) ⁽¹⁾ , ⁽⁹⁾		${\rm R_S}$ OCT with Calibration Setting, Ohm (Ω)		R _s OCT Without Calibration Setting, Ohm (Ω)		Cyclone IV E I/O Banks	Cyclone IV GX I/O Banks	Slew Rate Ontion	PCI- clamp Diode	
3.3-V LVTTL	Column I/O	Row I/O	Column I/O	Row I/O ⁽⁸⁾	Column I/O	Row I/O ⁽⁸⁾	Support	Support	(6)	Support	
3.3-V LVTTL	4,8	4,8	—		—				—	\checkmark	
3.3-V LVCMOS	2	2	—	_	_	_				\checkmark	
3.0-V LVTTL	4,8,12,16	4,8,12,16	50,25	50,25	50,25	50,25			019	\checkmark	
3.0-V LVCMOS	4,8,12,16	4,8,12,16	50,25	50,25	50,25	50,25			0,1,2	\checkmark	
3.0-V PCI/PCI-X	—	—	—	—	—	_		3,4,5,6,		~	
2.5-V LVTTL/LVCMOS	4,8,12,16	4,8,12,16	50,25	50,25	50,25	50,25		7,8,9		~	
1.8-V LVTTL/LVCMOS	2,4,6,8,10,12,1 6	2,4,6,8,10,12,1 6	50,25	50,25	50,25	50,25					
1.5-V LVCMOS	2,4,6,8,10,12,1 6	2,4,6,8,10,12,1 6	50,25	50,25	50,25	50,25				_	
1.2-V LVCMOS	2,4,6,8,10,12	2,4,6,8,10	50,25	50	50,25	50	1,2,3,4, 5,6,7,8	1,2,3,4, 4,5,6,7, 5,6,7,8 8	1,2,3,4, 4,5,6,7, 5,6,7,8 8		_
SSTL-2 Class I	8,12	8,12	50	50	50	50				—	
SSTL-2 Class II	16	16	25	25	25	25			012	—	
SSTL-18 Class I	8,10,12	8,10,12	50	50	50	50			0,1,2	—	
SSTL-18 Class II	12,16	12,16	25	25	25	25		3,4,5,6,		_	
HSTL-18 Class I	8,10,12	8,10,12	50	50	50	50		7,8,9		—	
HSTL-18 Class II	16	16	25	25	25	25				—	
HSTL-15 Class I	8,10,12	8,10,12	50	50	50	50				—	
HSTL-15 Class II	16	16	25	25	25	25					
HSTL-12 Class I	8,10,12	8,10	50	50	50	50		4,5,6,7, 8		_	
HSTL-12 Class II	14	—	25	—	25	—	3,4,7,8	4,7,8		—	
Differential SSTL-2 Class I ^{(2), (7)}	8,12	8,12	50	50	50	50				_	
Differential SSTL-2 Class II ^{(2),} ⁽⁷⁾	16	16	25	25	25	25					
Differential SSTL- 18 ^{(2), (7)}	8,10,12	_	50	_	50	_	1,2,3,4, 5,6,7,8	3,4,5,6, 7,8	0,1, 2		
Differential HSTL- 18 ^{(2),} (7)	8,10,12	_	50		50						
Differential HSTL- 15 ^{(2),} ⁽⁷⁾	8,10,12	—	50	—	50	—				_	
Differential HSTL- 12 (2), (7)	8,10,12	_	50	—	50	—	3,4,7,8	4,7,8		_	

Table 6–2. Cyclone IV Device I/O Features Support (Part 1 of 2)

Differential I/O Standards	I/O Bank Location	External Resistor Network at Transmitter	Transmitter (TX)	Receiver (RX)
	5,6	Not Required		
	3,4,5,6,7,8	Three Resistors	`	v
	5,6	Not Required		
RSDS	3,4,7,8	Three Resistors	✓	—
	3,4,5,6,7,8	Single Resistor		
mini-LVDS	5,6	Not Required		
	3,4,5,6,7,8	Three Resistors	`	—
סחמס	5,6	Not Required		
FFD3	3,4,5,6,7,8	Three Resistors	`	—
BLVDS (1)	3,4,5,6,7,8	Single Resistor	\checkmark	\checkmark
LVPECL (2)	3,4,5,6,7,8	—	—	\checkmark
Differential SSTL-2 ⁽³⁾	3,4,5,6,7,8	—	\checkmark	\checkmark
Differential SSTL-18 (3)	3,4,5,6,7,8	—	\checkmark	\checkmark
Differential HSTL-18 (3)	3,4,5,6,7,8	—	\checkmark	\checkmark
Differential HSTL-15 (3)	3,4,5,6,7,8	—	\checkmark	\checkmark
Differential HSTL-12 ⁽³⁾	4,5,6,7,8	—	~	\checkmark

Table 6–7. Differential I/O Standards Supported in Cyclone IV GX I/O Banks

Notes to Table 6-7:

(1) Transmitter and Receiver f_{MAX} depend on system topology and performance requirement.

(2) The LVPECL I/O standard is only supported on dedicated clock input pins.

(3) The differential SSTL-2, SSTL-18, HSTL-18, HSTL-15, and HSTL-12 I/O standards are only supported on clock input pins and PLL output clock pins. PLL output clock pins do not support Class II interface type of differential SSTL-18, HSTL-18, HSTL-15, and HSTL-12 I/O standards.

You can use I/O pins and internal logic to implement a high-speed differential interface in Cyclone IV devices. Cyclone IV devices do not contain dedicated serialization or deserialization circuitry. Therefore, shift registers, internal phase-locked loops (PLLs), and I/O cells are used to perform serial-to-parallel conversions on incoming data and parallel-to-serial conversion on outgoing data. The differential interface data serializers and deserializers (SERDES) are automatically constructed in the core logic elements (LEs) with the Quartus II software ALTLVDS megafunction.

Figure 6–14 shows a typical BLVDS topology with multiple transmitter and receiver pairs.



Figure 6-14. BLVDS Topology with Cyclone IV Devices Transmitters and Receivers

The BLVDS I/O standard is supported on the top, bottom, and right I/O banks of Cyclone IV devices. The BLVDS transmitter uses two single-ended output buffers with the second output buffer programmed as inverted, while the BLVDS receiver uses a true LVDS input buffer. The transmitter and receiver share the same pins. An output-enabled (OE) signal is required to tristate the output buffers when the LVDS input buffer receives a signal.

• For more information, refer to the *Cyclone IV Device Datasheet* chapter.

Designing with BLVDS

The BLVDS bidirectional communication requires termination at both ends of the bus in BLVDS. The termination resistor (R_T) must match the bus differential impedance, which in turn depends on the loading on the bus. Increasing the load decreases the bus differential impedance. With termination at both ends of the bus, termination is not required between the two signals at the input buffer. A single series resistor (R_S) is required at the output buffer to match the output buffer impedance to the transmission line impedance. However, this series resistor affects the voltage swing at the input buffer. The maximum data rate achievable depends on many factors.

- Altera recommends that you perform simulation using the IBIS model while considering factors such as bus loading, termination values, and output and input buffer location on the bus to ensure that the required performance is achieved.
- ***** For more information about BLVDS interface support in Altera devices, refer to *AN 522: Implementing Bus LVDS Interface in Supported Altera Device Families.*

Device	Package	Side	Number ×8 Groups	Number ×9 Groups	Number ×16 Groups	Number ×18 Groups	Number ×32 Groups	Number ×36 Groups
		Left	0	0	0	0	—	—
		Right	0	0	0	0	—	—
	144-pill EQFP	Bottom (1), (3)	1	0	0	0	—	—
		Top (1), (4)	1	0	0	0	—	—
		Left (1)	1	1	0	0	—	—
	OFC nin LIDCA	Right ⁽²⁾	1	1	0	0	—	—
EP46EZZ	200-piii 0BGA	Bottom	2	2	1	1	—	—
		Тор	2	2	1	1	—	—
		Left (1)	1	1	0	0	—	—
	256-pin FBGA	Right (2)	1	1	0	0	—	—
		Bottom	2	2	1	1	—	—
		Тор	2	2	1	1	—	—
	324-pin FBGA	Left (1)	2	2	1	1	0	0
ED40E20		Right (2)	2	2	1	1	0	0
EF40E30		Bottom	2	2	1	1	0	0
		Тор	2	2	1	1	0	0
		Left	4	4	2	2	1	1
	494 nin EPCA	Right	4	4	2	2	1	1
	404-piii FbGA	Bottom	4	4	2	2	1	1
EP4CE30		Тор	4	4	2	2	1	1
EP4CE115		Left	4	4	2	2	1	1
	780 pip EPCA	Right	4	4	2	2	1	1
	760-ріп ғыса	Bottom	6	6	2	2	1	1
		Тор	6	6	2	2	1	1
		Left	2	2	1	1	0	0
EDACEAO	324-nin FRGA	Right	2	2	1	1	0	0
	524-piii FBGA	Bottom	2	2	1	1	0	0
		Тор	2	2	1	1	0	0

Table 7–2. Cyclone IV E Device DQS and DQ Bus Mode Support for Each Side of the Device (Part 2 of 3)

Figure 7–7 illustrates Cyclone IV DDR input registers.



Figure 7–7. Cyclone IV DDR Input Registers

These DDR input registers are implemented in the core of devices. The DDR data is first fed to two registers, input register A_I and input register B_I .

- Input register A_I captures the DDR data present during the rising edge of the clock
- Input register B_I captures the DDR data present during the falling edge of the clock
- Register C_I aligns the data before it is synchronized with the system clock

The data from the DDR input register is fed to two registers, sync_reg_h and sync_reg_1, then the data is typically transferred to a FIFO block to synchronize the two data streams to the rising edge of the system clock. Because the read-capture clock is generated by the PLL, the read-data strobe signal (DQS or CQ) is not used during read operation in Cyclone IV devices; hence, postamble is not a concern in this case.

Figure 8–11 shows the recommended balanced star routing for multiple bus master interfaces to minimize signal integrity issues.





Notes to Figure 8-11:

- (1) Altera recommends that *M* does not exceed 6 inches, as listed in Table 8–11 on page 8–28.
- (2) Altera recommends using a balanced star routing. Keep the *N* length equal and as short as possible to minimize reflection noise from the transmission line. The *M* length is applicable for this setup.

Estimating AP Configuration Time

AP configuration time is dominated by the time it takes to transfer data from the parallel flash to Cyclone IV E devices. This parallel interface is clocked by the Cyclone IV E DCLK output (generated from an internal oscillator). The DCLK minimum frequency when using the 40-MHz oscillator is 20 MHz (50 ns). In word-wide cascade programming, the DATA [15..0] bus transfers a 16-bit word and essentially cuts configuration time to approximately 1/16 of the AS configuration time. Equation 8–4 and Equation 8–5 show the configuration time calculations.

Equation 8-4.

Size $\times \left(\frac{\text{maximum DCLK period}}{16 \text{ bits per DCLK cycle}}\right)$ = estimated maximum configuration time

Equation 8-5.

9,600,000 bits ×
$$\left(\frac{50 \text{ ns}}{16 \text{ bit}}\right)$$
 = 30 ms

Transmitter Channel Datapath

The following sections describe the Cyclone IV GX transmitter channel datapath architecture as shown in Figure 1–3:

- TX Phase Compensation FIFO
- Byte Serializer
- 8B/10B Encoder
- Serializer
- Transmitter Output Buffer

TX Phase Compensation FIFO

The TX phase compensation FIFO compensates for the phase difference between the low-speed parallel clock and the FPGA fabric interface clock, when interfacing the transmitter channel to the FPGA fabric (directly or through the PIPE and PCIe hard IP). The FIFO is four words deep, with latency between two to three parallel clock cycles. Figure 1–4 shows the TX phase compensation FIFO block diagram.

Figure 1–4. TX Phase Compensation FIFO Block Diagram



Note to Figure 1-4:

(1) The x refers to the supported 8-, 10-, 16-, or 20-bits transceiver channel width.

- The FIFO can operate in registered mode, contributing to only one parallel clock cycle of latency in Deterministic Latency functional mode. For more information, refer to "Deterministic Latency Mode" on page 1–73.
- **To** For more information about FIFO clocking, refer to "FPGA Fabric-Transceiver Interface Clocking" on page 1–43.

Byte Serializer

The byte serializer divides the input datapath width by two to allow transmitter channel operation at higher data rates while meeting the maximum FPGA fabric frequency limit. This module is required in configurations that exceed the maximum FPGA fabric-transceiver interface clock frequency limit and optional in configurations that do not.

• For the FPGA fabric-transceiver interface frequency specifications, refer to the *Cyclone IV Device Data Sheet*.

 Bit reversal—reverses the transmit bit order from LSB-to-MSB (default) to MSB-to-LSB at the input to the serializer. For example, input data to serializer D[7..0] is rewired to D[0..7] for 8-bit data width, and D[9..0] is rewired to D[0..9] for 10-bit data width. Figure 1–10 shows the transmitter bit reversal feature.



Figure 1–10. Transmitter Bit Reversal Operation in Basic Single-Width Mode

- Input bit-flip—reverses the bit order at a byte level at the input of the transmitter phase compensation FIFO. For example, if the 16-bit parallel transmitter data at the tx_datain port is '10111100 10101101' (16'hBCAD), selecting this option reverses the input data to the transmitter phase compensation FIFO to '00111101 10110101' (16'h3DB5).
- Bit-slip control—delays the data transmission by a number of specified bits to the serializer with the tx_bitslipboundaryselect port. For usage details, refer to the "Transmit Bit-Slip Control" on page 1–76.

Serializer

The serializer converts the low-speed parallel 8-bit or 10-bit data from the transmitter PCS to high-speed serial data for the transmitter output buffer. The serializer operates with a high-speed clock at half of the serial data rate. The serializer transmission sequence is LSB to MSB.

Clock Data Recovery

Each receiver channel has an independent CDR unit to recover the clock from the incoming serial data stream. The high-speed recovered clock is used to clock the deserializer for serial-to-parallel conversion of the received input data, and low-speed recovered clock to clock the receiver PCS blocks. Figure 1–15 illustrates the CDR unit block diagram.





Notes to Figure 1-15:

- (1) Optional RX local divider for CDR clocks from multipurpose PLL is only available in each CDR unit for EP4CGX30 (F484 package), EP4CGX50, and EP4CGX75 devices. This block is used with the transceiver dynamic reconfiguration feature. For more information, refer to the Cyclone IV Dynamic Reconfiguration chapter and AN 609: Implementing Dynamic Reconfiguration in Cyclone IV GX Devices.
- (2) CDR state transition in automatic lock mode is not dependent on rx_signaldetect signal, except when configured in PCI Express (PIPE) mode only.

Each CDR unit gets the reference clock from one of the two multipurpose phase-locked loops (PLLs) adjacent to the transceiver block. The CDR works by tracking the incoming data with a phase detector and finding the optimum sampling clock phase from the phase interpolator unit. The CDR operations are controlled by the LTR/LTD controller block, where the CDR may operate in the following states:

- Lock-to-reference (LTR) state—phase detector disabled and CDR ignores incoming data
- Lock-to-data (LTD) state—phase detector enabled and CDR tracks incoming data to find the optimum sampling clock phase

State transitions are supported with automatic lock mode and manual lock mode.

Automatic Lock Mode

Upon receiver power-up and reset cycle, the CDR is put into LTR state. Transition to the LTD state is performed automatically when both of the following conditions are met:

- Signal detection circuitry indicates the presence of valid signal levels at the receiver input buffer. This condition is valid for PCI Express (PIPE) mode only. CDR transitions are not dependent on signal detection circuitry in other modes.
- The recovered clock is within the configured part per million (ppm) frequency threshold setting with respect to the CDR clocks from multipurpose PLL.

Channel Configuration		Quartus II Selection
Bonded	With rate match FIFO ⁽¹⁾	coreclkout clock feeds the FIFO read clock for the bonded channels. coreclkout clock is the common bonded low-speed clock, which also feeds the FIFO read clock and transmitter PCS in the bonded channels.
	Without rate match FIFO	<code>rx_clkout</code> clock feeds the FIFO read clock. <code>rx_clkout</code> is forwarded through the receiver channel from low-speed recovered clock, which also feeds the FIFO write clock.

Table 1–13. Automatic RX Phase Compensation FIFO Read Clock Selection (Part 2 of 2)

Note to Table 1-13:

(1) Configuration with rate match FIFO is supported in transmitter and receiver operation.

When using user-specified clock option, ensure that the clock feeding rx_coreclk port has 0 ppm difference with the RX phase compensation FIFO write clock.

Calibration Block

This block calibrates the OCT resistors and the analog portions of the transceiver blocks to ensure that the functionality is independent of process, voltage, and temperature (PVT) variations.

Figure 1–40 shows the location of the calibration block and how it is connected to the transceiver blocks.

Figure 1–40. Transceiver Calibration Blocks Location and Connection



Note to Figure 1-40:

(1) Transceiver block GXBL1 is only available for devices in F484 and larger packages.

Table 2–2 lists the power-down signals available for each transceiver block.

 Table 2–2.
 Transceiver Block Power-Down Signals

Signal	Description				
	Resets the transceiver PLL. The pll_areset signal is asserted in two conditions:				
pll_areset	 During reset sequence, the signal is asserted to reset the transceiver PLL. This signal is controlled by the user. 				
	 After the transceiver PLL is reconfigured, the signal is asserted high by the ALTPLL_RECONFIG controller. This signal is not controlled by the user. 				
axp powerdown	Powers down the entire transceiver block. When this signal is asserted, this signal powers down the PCS and PMA in all the transceiver channels.				
gxb_powerdown	This signal operates independently from the other reset signals. This signal is common to the transceiver block.				
nll locked	A status signal. Indicates the status of the transmitter multipurpose PLLs or general purpose PLLs.				
pii_iocked	 A high level—indicates the multipurpose PLL or general purpose PLL is locked to the incoming reference clock frequency. 				
	A status signal. Indicates the status of the receiver CDR lock mode.				
rx_freqlocked	 A high level—the receiver is in lock-to-data mode. 				
	 A low level—the receiver CDR is in lock-to-reference mode. 				
busy	A status signal. An output from the ALTGX_RECONFIG block indicates the status of the dynamic reconfiguration controller. This signal remains low for the first reconfig_clk clock cycle after power up. It then gets asserted from the second reconfig_clk clock cycle. Assertion on this signal indicates that the offset cancellation process is being executed on the receiver buffer as well as the receiver CDR. When this signal is deasserted, it indicates that offset cancellation is complete.				
	This busy signal is also used to indicate the dynamic reconfiguration duration such as in analog reconfiguration mode and channel reconfiguration mode.				

For more information about offset cancellation, refer to the *Cyclone IV Dynamic Reconfiguration* chapter.

IF If none of the channels is instantiated in a transceiver block, the Quartus[®] II software automatically powers down the entire transceiver block.

Blocks Affected by the Reset and Power-Down Signals

Table 2–3 lists the blocks that are affected by specific reset and power-down signals.

Table 2-3.	. Blocks Affected by Reset and Pov	wer-Down Signals	(Part 1 of 2)
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Transceiver Block	rx_digitalreset	rx_analogreset	tx_digitalreset	pll_areset	gxb_powerdown
multipurpose PLLs and general purpose PLLs	_	—	_	\checkmark	_
Transmitter Phase Compensation FIFO	_	_	~	_	~
Byte Serializer	—	—	~	_	~
8B/10B Encoder	—	—	~	—	\checkmark

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Cyclone IV Device Handbook, Volume 3 A DC signal is equivalent to 100% duty cycle. For example, a signal that overshoots to 4.3 V can only be at 4.3 V for 65% over the lifetime of the device; for a device lifetime of 10 years, this amounts to 65/10ths of a year.

Symbol	Parameter	Condition (V)	Overshoot Duration as % of High Time	Unit
		V ₁ = 4.20	100	%
V _i AC Input Voltage	V ₁ = 4.25	98	%	
		V ₁ = 4.30	65	%
		V ₁ = 4.35	43	%
	V ₁ = 4.40	29	%	
	Voltago	V ₁ = 4.45	20	%
		$V_1 = 4.50$	13	%
		V ₁ = 4.55	9	%
		$V_1 = 4.60$	6	%

Table 1–2. Maximum Allowed Overshoot During Transitions over a 10-Year Time Frame for Cyclone IV Devices

Figure 1–1 shows the methodology to determine the overshoot duration. The overshoot voltage is shown in red and is present on the input pin of the Cyclone IV device at over 4.3 V but below 4.4 V. From Table 1–2, for an overshoot of 4.3 V, the percentage of high time for the overshoot can be as high as 65% over a 10-year period. Percentage of high time is calculated as ([delta T]/T) × 100. This 10-year period assumes that the device is always turned on with 100% I/O toggle rate and 50% duty cycle signal. For lower I/O toggle rates and situations in which the device is in an idle state, lifetimes are increased.





Parameter	Condition	V _{CCIO} (V)												
		1.2		1	1.5 1		1.8 2		2.5		3.0		3.3	
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus hold trip point	_	0.3	0.9	0.375	1.125	0.68	1.07	0.7	1.7	0.8	2	0.8	2	V

Table 1–7. Bus Hold Parameter for Cyclone IV Devices (Part 2 of 2)⁽¹⁾

Note to Table 1-7:

(1) Bus hold trip points are based on the calculated input voltages from the JEDEC standard.

OCT Specifications

Table 1–8 lists the variation of OCT without calibration across process, temperature, and voltage (PVT).

Table 1–8. Series OCT Without Calibration Specifications for Cyclone IV Devices

		Resistance		
Description	V _{CCIO} (V)	Commercial Maximum	Industrial, Extended industrial, and Automotive Maximum	Unit
	3.0	±30	±40	%
	2.5	±30	±40	%
Series OCT without calibration	1.8	±40	±50	%
	1.5	±50	±50	%
	1.2	±50	±50	%

OCT calibration is automatically performed at device power-up for OCT-enabled I/Os.

Table 1–9 lists the OCT calibration accuracy at device power-up.

Table 1–9.	Series OCT v	with Calibration	at Device Power-Up	o Specifications fo	r Cyclone IV
Devices ⁽¹⁾					

		Calibration Accuracy				
Description	V _{CCIO} (V)	Commercial Maximum	Industrial, Extended industrial, and Automotive Maximum	Unit		
	3.0	±10	±10	%		
Series OCT with	2.5	±10	±10	%		
calibration at device	1.8	±10	±10	%		
power-up	1.5	±10	±10	%		
	1.2	±10	±10	%		

Note to Table 1-9:

(1) This specification is not applicable to EP4CGX15, EP4CGX22, and EP4CGX30 devices.